

# METAL-SEMICONDUCTOR CONTACTS IN A NUTSHELL

### [PHT.301UF] Physics of Semiconductor Devices (17W)

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Physics of Semiconductor Devices

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### **BASICS: WORK FUNCTION OF A METAL**



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Metal: free electrons among a lattice of positively charged ions **WORK FUNCTION**  $\phi_m$  [V] Minimum energy to remove an electron from the solid surface.

Element		$e \phi_m$ [1]
Al	aluminum	4.06 - 4.26
Ag	silver	4.26 - 4.74
W	tungsten	4.32 – 5.22
Cu	copper	4.53 – 5.10
Αu	gold	5.10 - 5.47
Pt	platinum	5.12 – 5.93

Physics of Semiconductor Devices [1] Editor-in-Chief John R. Rumble. CRC Handbook of Chemistry and Physics.



3

## **BASICS: WORK FUNCTION VS ELECTRON AFFINITY**



**ELECTRON AFFINITY**  $\chi_s$  [V]  $\chi_s = E_{vac} - E_c$ 

**VACUUM LEVEL**  $E_{vac}$  [V] Energy level where the electrons are freed from the surfaces' forces.

Element		$e\chi_s$ <sup>[2]</sup>
AlAs	aluminum arsenide	3.5
GaAs	gallium arsenide	4.07
Si	silicon	4.01
Ge	germanium	4.13









# **N-TYPE OHMIC CONTACT**

 $\phi_s > \phi_m : E_c \text{ and } E_v \text{ bend up}$ 



With a correct combination of materials we could obtain a nearohmic behavior.

<u>E.g.</u>: n-type + **Ca** or **Ba** (low  $\phi_m$ ) p-type + **Pt** or **Au** (high  $\phi_m$ )

Low resistance contacts are difficult to form in **Si**, **Ge**, **GaAs** due to interface states (Fermi level pinning).









Ohmic contacts form more easily when the semiconductor is highly doped nearby the junction.

A high doping narrows the depletion region and increases the probability for tunneling significantly.

This behavior is commonly used for creating metal contacts to the outside.





Physics of Semiconductor Devices

[2] Jasprit Singh. Semiconductor Devices. Basic Principles.





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### **SCHOTTKY DIODE FACTS**



#### **INTERFACE STATES**

Usually, metal and semiconductor consist out of different crystal structures. Therefore, there are many broken bonds at the interface. Those act like dopants and cause a Fermi level pinning phenomenon.

### Schottky diode (Si) U pn-junction diode (Si)

#### SWITCHING SPEED

Schottky diodes are majority carrier devices and are faster than pn-junction diodes because no slow random recombination takes place.

#### **VOLT-AMPERE CHARACTERISTICS**

The value of the forward voltage is minimal in Schottky diodes. However, it possesses a higher leakage current. In addition, the reverse breakdown voltage is also small.

#### CAPACITANCE-VOLT MEASUREMENTS [3]

Due to the abrupt junction, the depletion width only increases in the semiconductor. Therefore, the doping concentration can be calculated easily: ( $N_x = N_A$  if p-type;  $N_x = N_D$  if n-type)

$$W = \frac{\varepsilon}{C_j} = \sqrt{\frac{2 \cdot \varepsilon \cdot (U_{bi} - U)}{e \cdot N_x}}$$